

H1 NY PMS 440 0025 PH
 H2 NY PMS 440 0025 PH
 H3 NY PMS 440 0025 PH
 H4 NY PMS 440 0025 PH

H5 1902C
 H6 1902C
 H7 1902C
 H8 1902C

FID1
 FID2
 FID3

PCB LOGO
 Texas Instruments

PCB LOGO
 Pb-Free Symbol

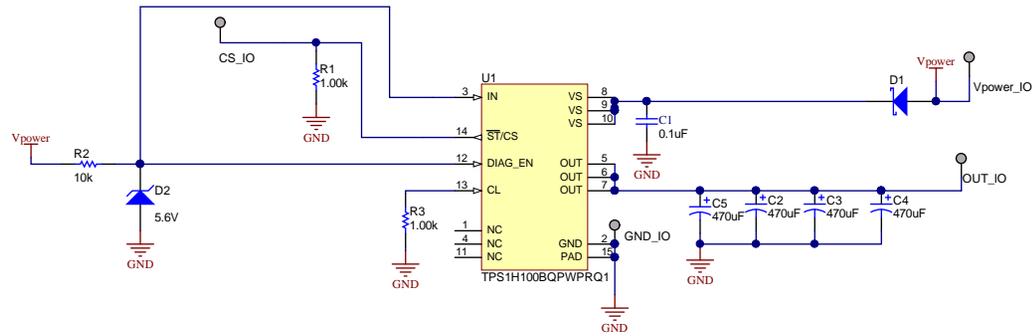
Label Table	
Variant	Label Text
001	ChangeMe!
002	ChangeMe!

ZZ1
Label Assembly Note
 This Assembly Note is for PCB labels only

ZZ2
Assembly Note
 These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
 These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



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Number: TIDA-00866 | Rev: E1
 SVN Rev: Version control disabled
 Drawn By: Alex Wang
 Engineer: Enter name of project lead

Designed for: Public Release | Mod. Date: 3/1/2016
 Project Title: TPS1H100-Q1 40-V, 100-mA, Smart High-Side Swit
 Sheet Title:
 Assembly Variant: [No Variations] | Sheet: 1 of 1
 File: TIDA-00866.SchDoc | Size: A4
 Contact: <http://www.ti.com/support>



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Layer Name	Gerber Document	Copper Thickness	Dielectric Material
Top Solder Mask	(.OTS)		Solder Resist
Top Layer	(.GTL)	2.0mil	
MidLayer1	(.G1)	1.4mil	FR-4
MidLayer2	(.G2)	1.4mil	FR-4
Bottom Layer	(.GBL)	2.0mil	
Bottom Solder Mask	(.GBS)		Solder Resist

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 ML
 MIN. CLEARANCE: 0.2 mm
 MIN. VIA PAD SIZE: 24 ML
 MINIMUM ANNUAL RING: 0.05mm (2ML) EXTERNAL
 PER IPC-D-275 CLASS 2 LEVEL C
 REGISTRATION TOLERANCES: METAL +/- 5 ML HOLES +/- 3 ML

MATERIAL:
 FR-40B FR-4 High Tg OTHER _____
 THICKNESS: 82 ML (1.6mm) +/-10% OTHER _____
 TOLERANCE: ANSI IPC-6012 TYPE 3 CLASS 2 OTHER +/- _____
 BOW & TWIST: ANSI IPC-6012 TYPE 3 CLASS 2 OTHER +/- _____

DRILLING:
 REFERENCE: AS SHOWN NC_DRILL FLES
 PTH MIN COPPER THICKNESS: 1ML OTHER _____

BOARD FINISH:
 SILKSCREEN COLOR: TOP BOTTOM
 WHITE OTHER _____
 SOLDER RESIST COLOR: GREEN BLUE OTHER _____

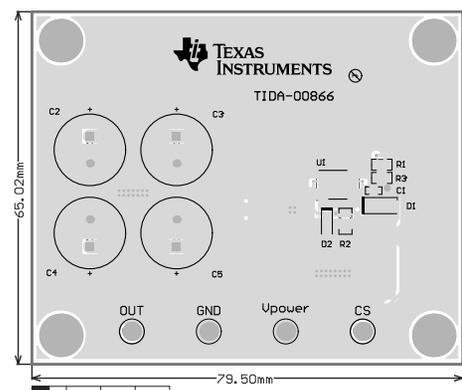
SURFACE FINISH: IMMERSION GOLD (ENIG) ENIG
 IMM. TIN/SILVER OR EQUIV OTHER _____

ARRAY/PANEL: CUT AND TRIM PER MECH LAYER 1
 N.C. ROUTE V. SCORE

CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBs TO MEET OR EXCEED THE REQUIREMENTS OF:
 ANSI PC-A-600F CLASS -> 1 2 3
 UL 94V-0 RoHS OTHER PER ORDER

ADDITIONAL REQUIREMENTS: MICROSECTION: YES
 BARE BOARD ELEC. TEST: NONE REQUIRED PER ORDER
 MANUFACTURER'S UL: RAL METAL SILK

Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.
 Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.
 Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.
 Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.
 ASSEMBLY VARIANT: [No Variations]

REV	DESCRIPTION	DATE	BY	APP'D	DATE	BY	APP'D	DATE	BY	APP'D
1	Initial Release	10/15/10	JWA		10/15/10	JWA		10/15/10	JWA	

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ENGINEER:	LAYOUT BY:
Enter name of project lead	Who did the Layout?
SCALE: 1:00	ALTIM DESIGNER VERSION: 16.0.1.192

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